1H, 2023 Investor Conference

尼得科超眾科技股份有限公司
Nidec Chaun-Choung Technology Corp.

Date: Aug. 25th, 2023

Nidec Chaun-Choung Technology Corporation

Disclaimer

This presentation of NCCI contains forward-looking statements subject to risks and uncertainties. Actual results may differ materially from the contained in the forward-looking statements.

The forward-looking statements in this presentation are the current belief of NCCI as of the date for this release, and NCCI has no obligation to update the forward-looking statements for new information, future events, or otherwise.

Agenda

- Company Profile
- 1H, 2023 Financial Results
- Focus: Market, Products & Technologies
- Q & A

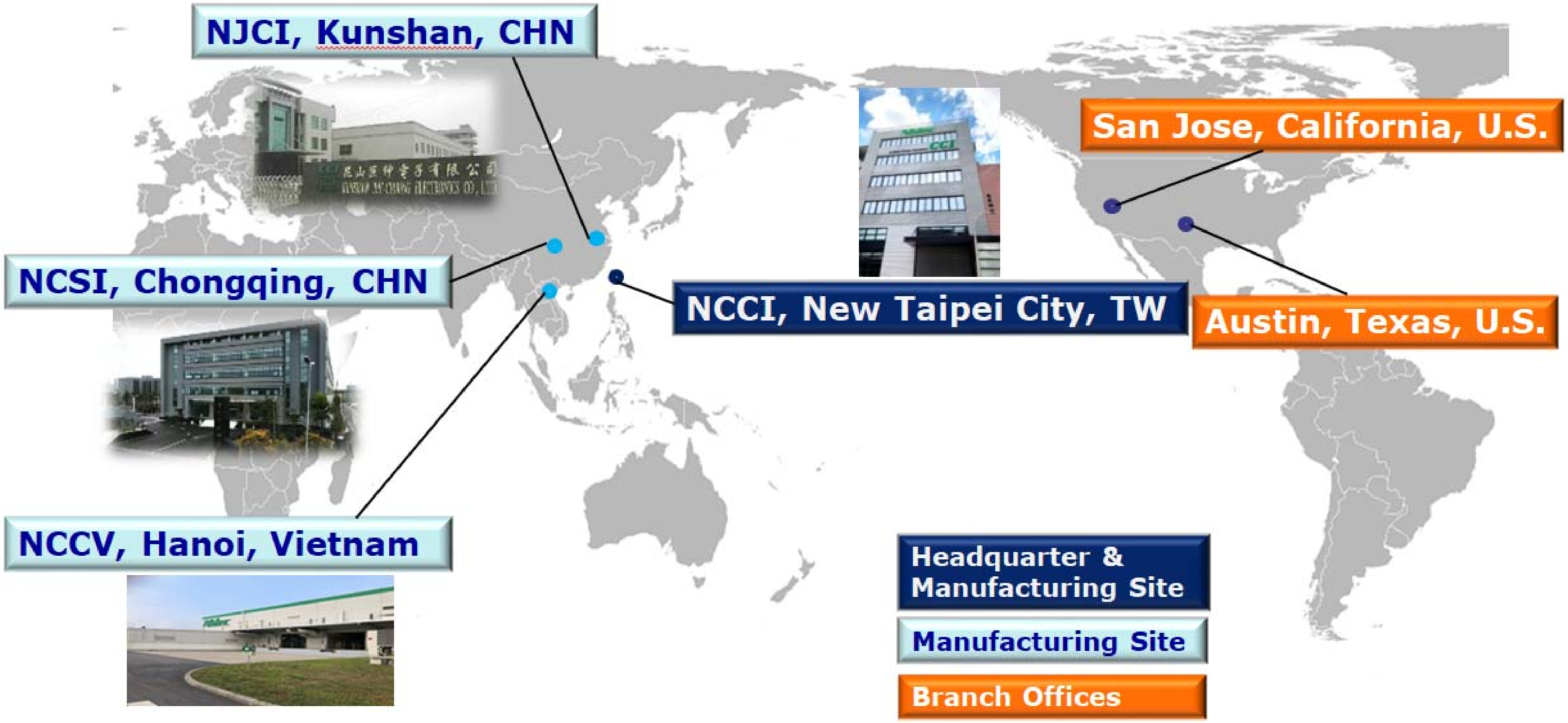
Company Profile

- **Chairman and CEO：** Nagai Junichi
- **Founded :** Dec.14. 1973
- **Stock Listing：** TWSE (ticker: 6230)
- **Nidec Corporation:**

  Hold 86.3% shares, as a major shareholder (Jul. 2023).
- **Capital :** NT$ 863,434 (K)
- **HQ Address :** No. 184-3, Zhongxing N. St., Sanchong Dist.,

  New Taipei City 241, Taiwan
- **Main Business :** Heat Sink & Thermal Solutions
- **WW Factories & Offices**

Worldwide Factories & Offices



NJCI, Kunshan, CHN

NCSI, Chongqing, CHN

NCCV, Hanoi, Vietnam

NCCI, New Taipei City, TW

San Jose, California, U.S.

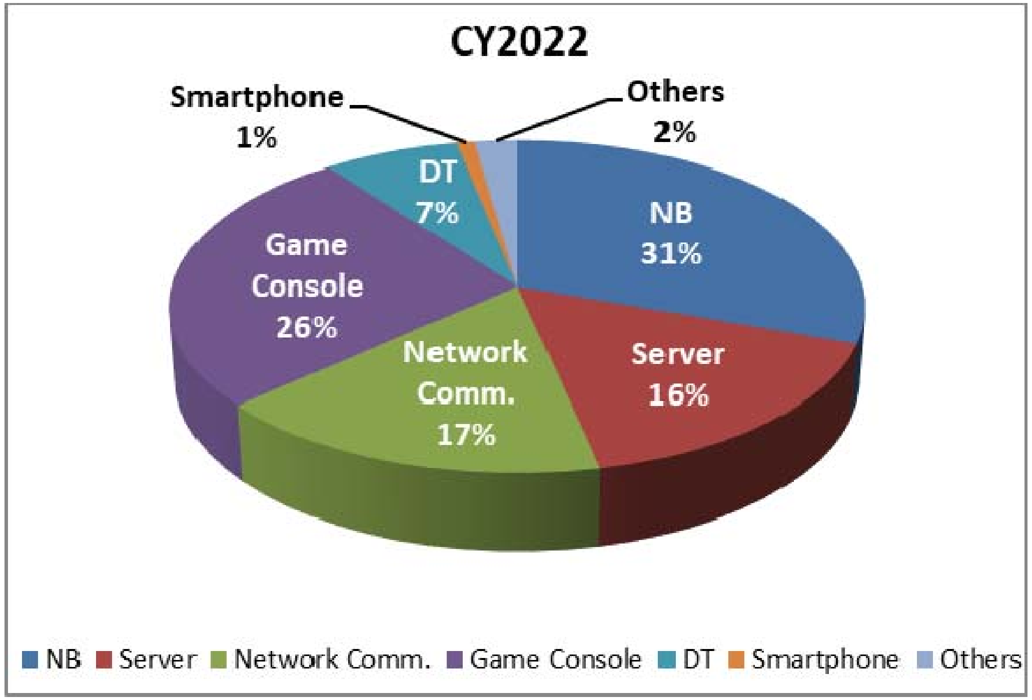
Austin, Texas, U.S.

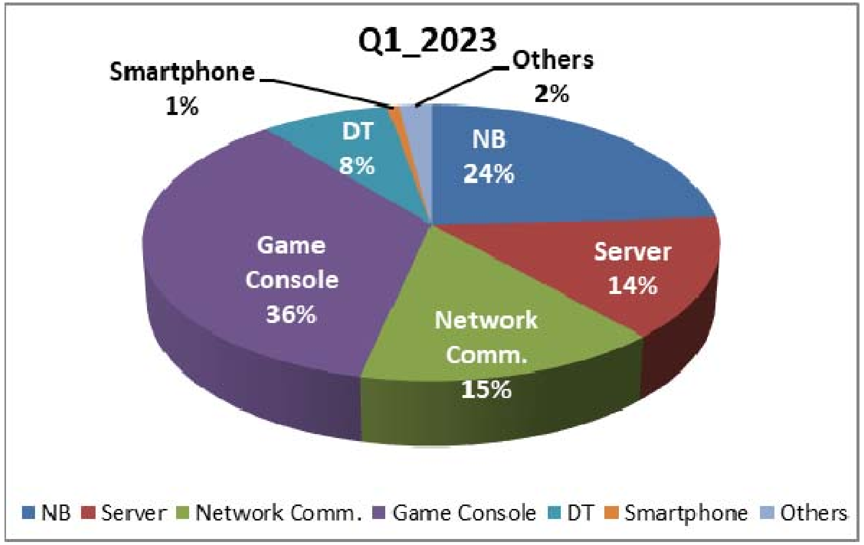
Headquarter & Manufacturing Site

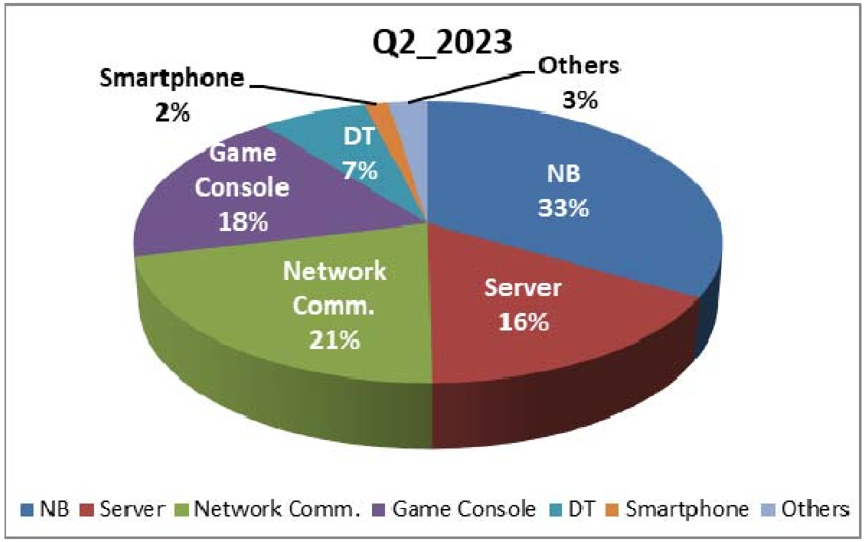
Manufacturing Site

Branch Offices

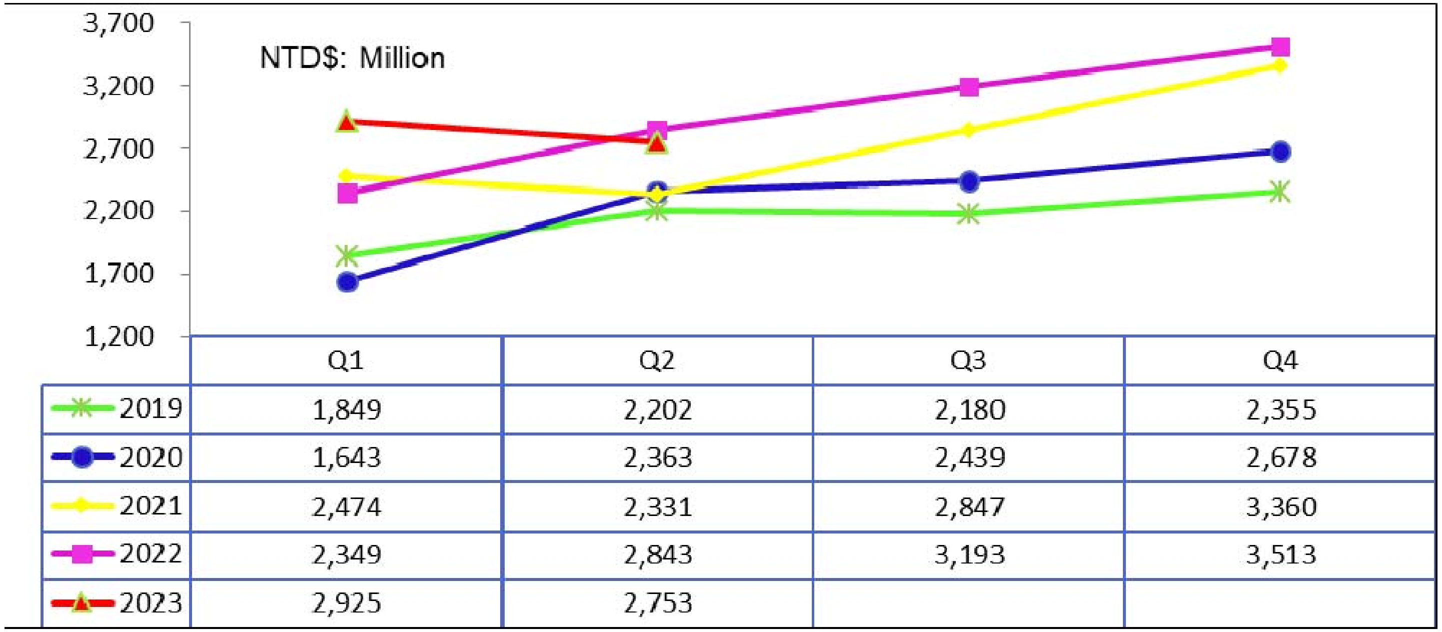
Financial result-Product Mix







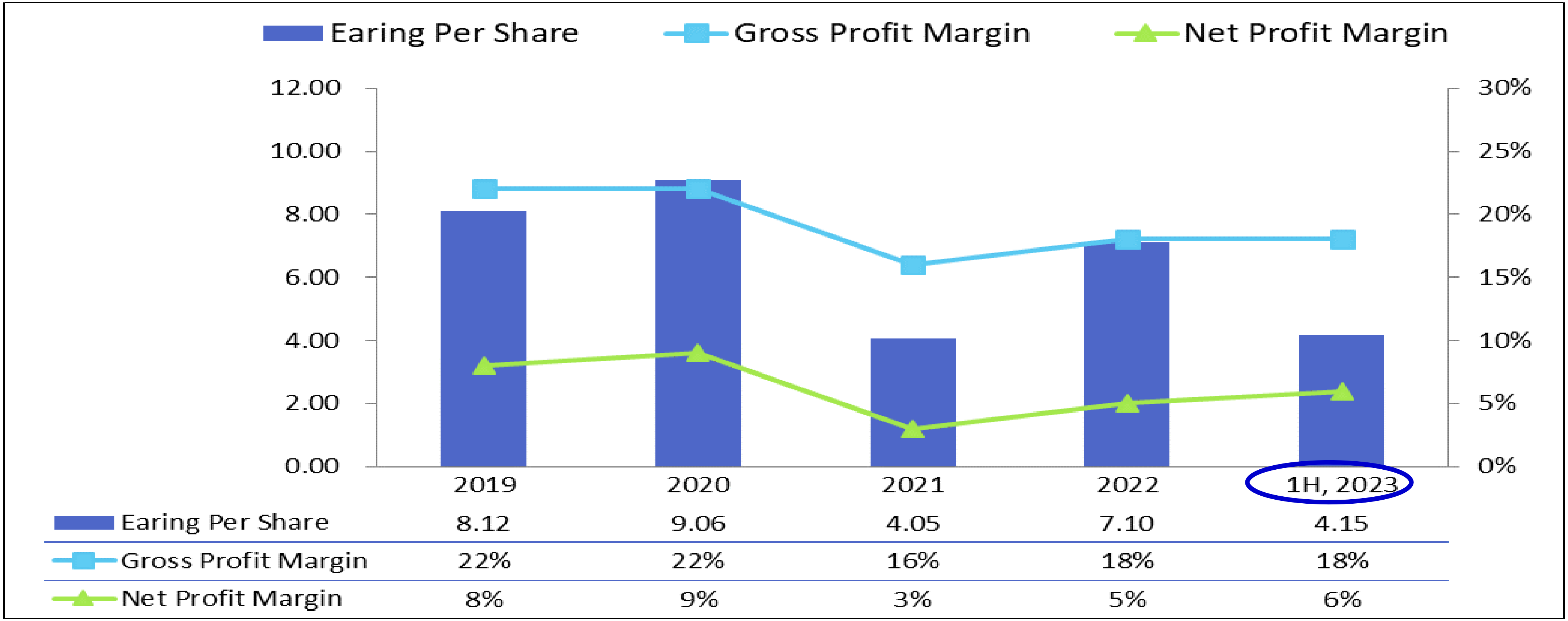
Financial Result-Revenue



	Q1	Q2	Q3	Q4
2019	1,849	2,202	2,180	2,355
2020	1,643	2,363	2,439	2,678
2021	2,474	2,331	2,847	3,360
2022	2,349	2,843	3,193	3,513
2023	2,925	2,753		

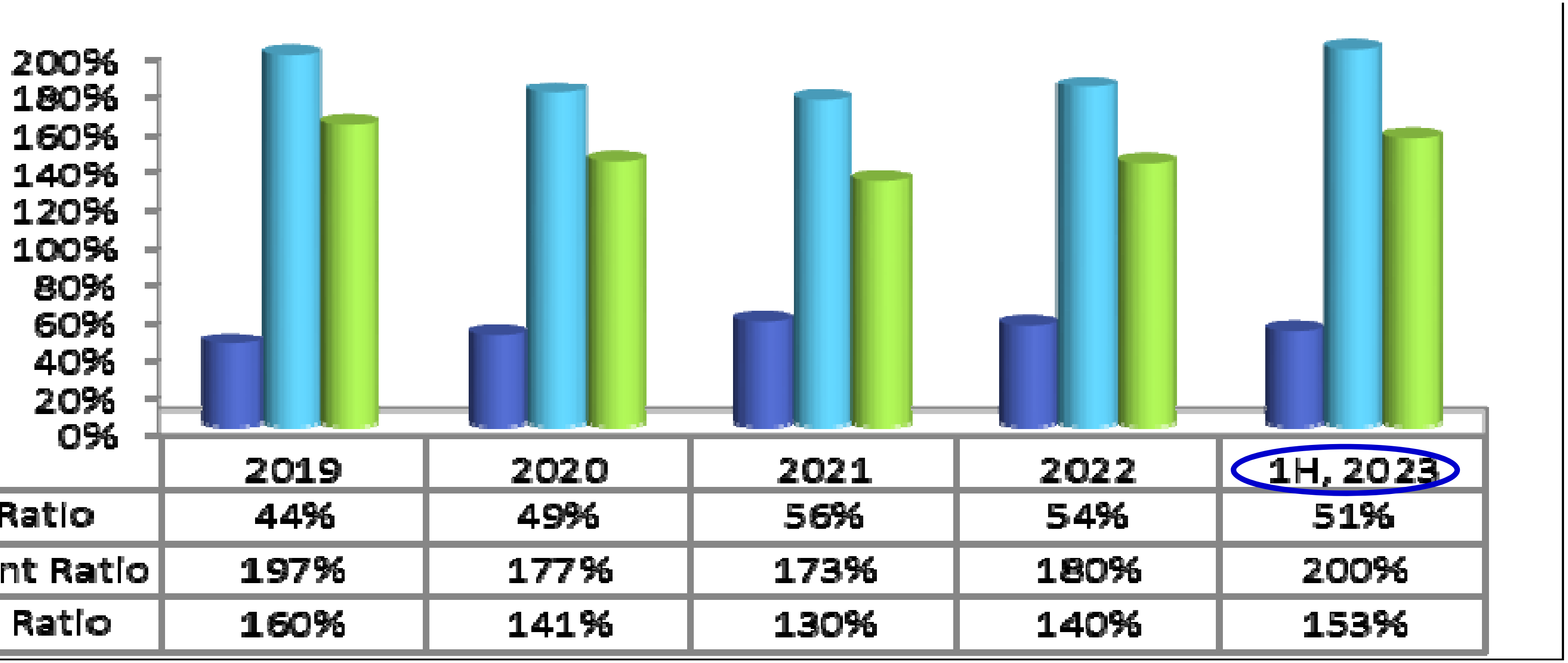
NTD$: Million

Financial Result-Financial Index I.



	2019	2020	2021	2022	1H, 2023
Earing Per Share	8.12	9.06	4.05	7.10	4.15
Gross Profit Margin	22%	22%	16%	18%	18%
Net Profit Margin	8%	9%	3%	5%	6%

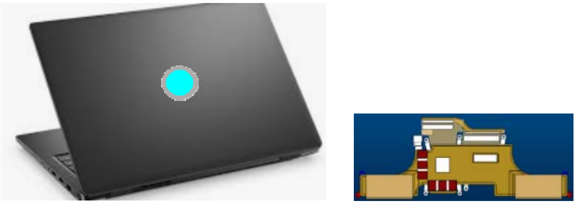
Financial Result-Financial Index II



	2019	2020	2021	2022	1H, 2023
🟦 Debt Ratio	44%	49%	56%	54%	51%
🟦 Current Ratio	197%	177%	173%	180%	200%
🟩 Quick Ratio	160%	141%	130%	140%	153%

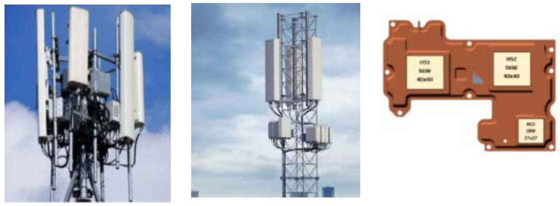
Focus Market

Heat Transfer Core Technology



PC: NB / DT

5G : Network/Telecom.

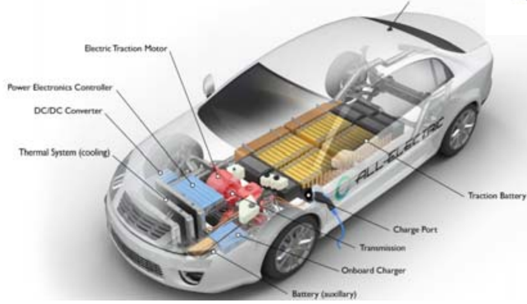


HPC

Gaming

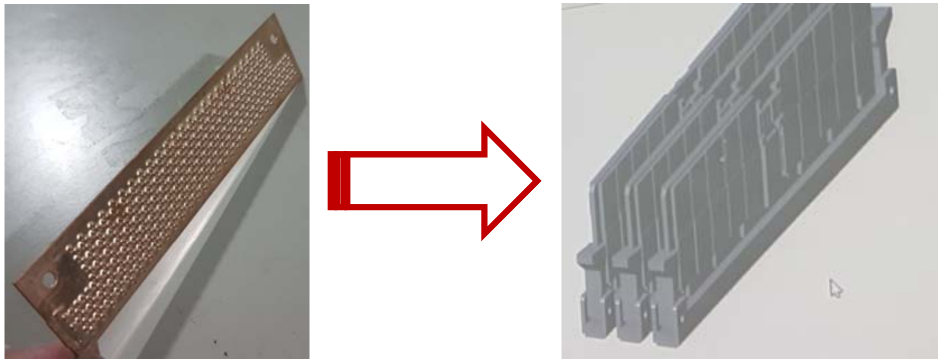
Portable Devices

Automotive (EV)

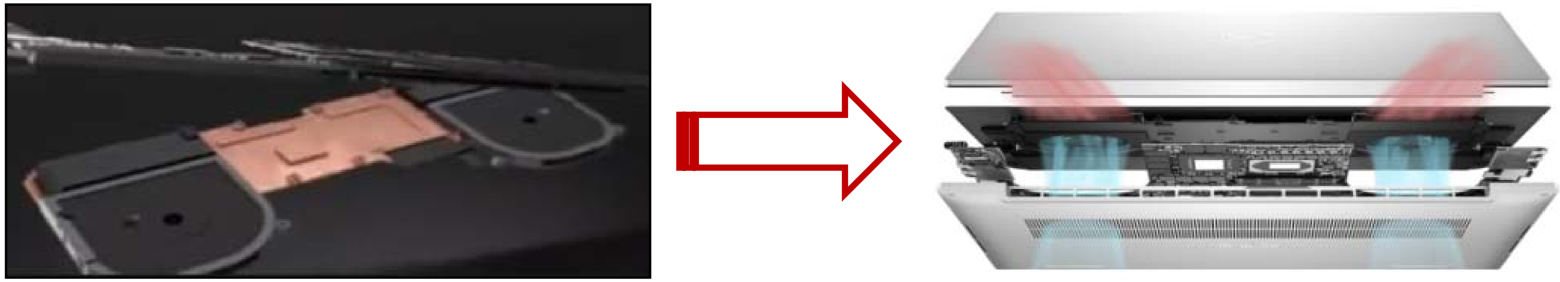


Focus Developing Products - I

- **Slim Thermal Solution for DRAM**
  Ultra Thin VC ($t<1.0$mm) for 6 Watts

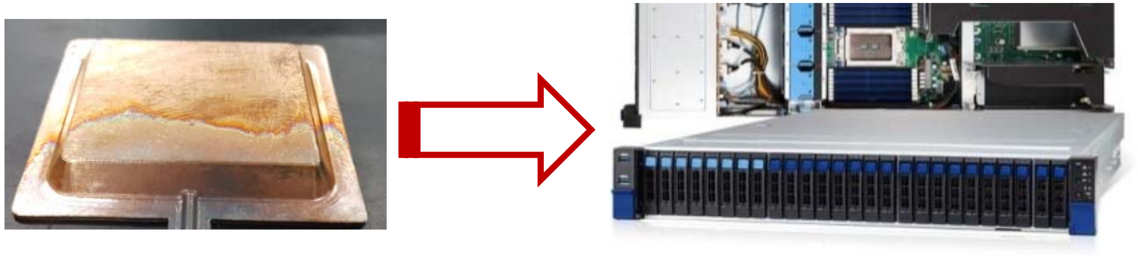


- **Slim Thermal Solution for Gaming NB**
  Slim VC (1.0mm$\leq$ t $\leq$2.0mm) for CPU+GPU 140 Watts

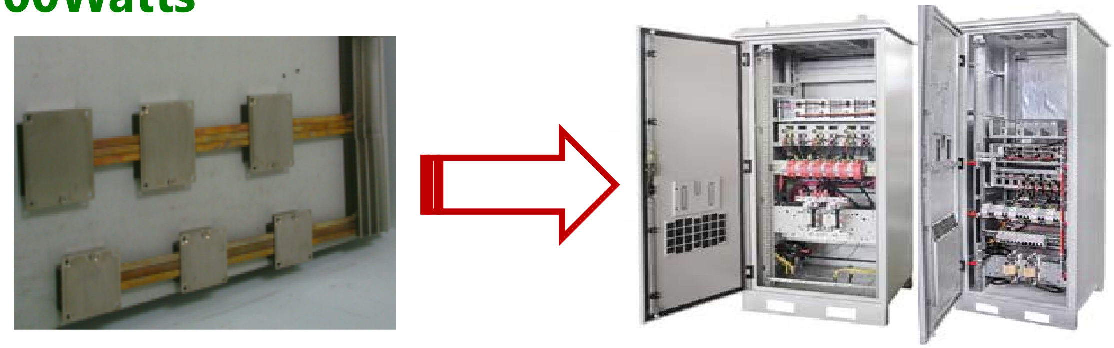


Focus Developing Products - II

- **Hi-Power VC Thermal Solution for HPC Server**
  High Heat Flux Vapor Chamber > 80 W/cm^2

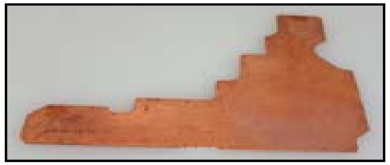


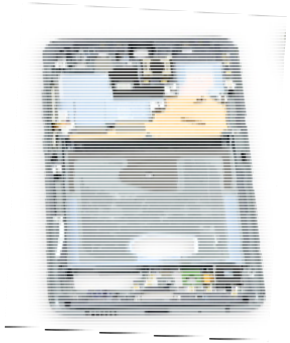
- **Hi-power Heat Pipe Module for 5G Telecom Switch**
  Long Heat Pipe L ≥ 600 mm for 500Watts



Focus Developing Products - III

- **Ultra-thin Thermal Solution for 5G Smart Phone**
  · VC Thickness 0.25mm – 0.35mm

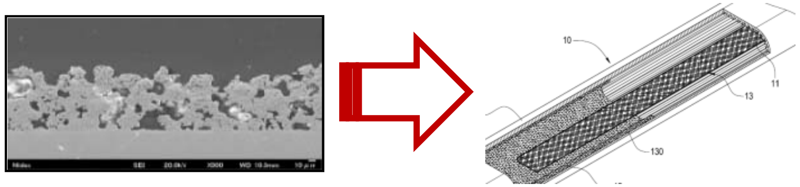




- **IGBT (Insulated Gate Bipolar Transistor) Thermal Solution - Electric Vehicle**
  · 45KW, Cold Plate

Competitive Advantages

- **Metallurgy & Wick Technology –**

  Nidec & NCCI team with strong basic research and Proprietary multi-wick design to support Ultra-thin / Hi-power Thermal Solutions.

- **Automation Equipment Building in House –**

  Nidec & NCCI team up to develop manufacturing machine from sample to mass production, and know-how in house.

- **Active & Passive Horizontal Division of Collaborating –**

  Nidec is good at Fan/Pump active solution and NCCI is good at HP/VC passive solution, collaboration to provide customer total solution with best options.